

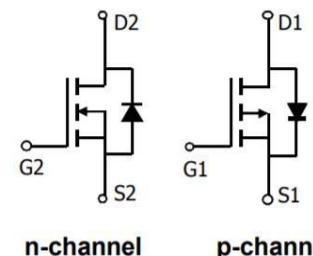
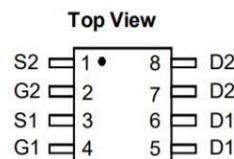
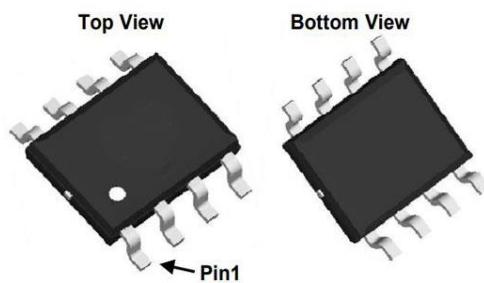
General Description

N+P Complementary Power MOSFET

Very low on-resistance RDS(on) @ VGS=4.5 V

Pb-free lead plating; RoHS compliant

	N channel	P channel	
V _{DS}	30	-30	V
R _{D(on)} , TYP@VGS=10V	29.4	37.8	mΩ
R _{D(on)} , TYP@VGS=4.5	46.2	37.8	mΩ
I _D	6	-7	A



Part ID	Package Type	Marking	Tape and reel infomation
AC4606	SOP8	7N03C	3000



100% UIS Tested

Parameter	Symbol	Max N-channel	Max P-channel	Units
Drain-Source Voltage	V _{DS}	30	-30	V
Gate-Source Voltage	V _{GS}	20	20	±V
Continuous Drain Current A	I _D	6	-7	A
		5	-5.5	
Pulsed Drain Current B	I _{DM}	9.6	-11.2	A
Avalanche Current G	I _{AR}	1.92	-2.2	
Repetitive avalanche energy L=0.1mH G	E _{AR}	4.416	-5.2	mJ
Power Dissipation A	P _D	2	3.1	W
		1.3	2	
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient A	t ≤ 10s	105	157	°C/W
Maximum Junction-to-Ambient A		210	252	°C/W
Maximum Junction-to-Lead c	R _{θJL}	63	100	°C/W

STATIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV _{DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V			1	uA
					5	
I _{GSS}	Gate-Body leakage current	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
V _{G(S(th))}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250μA	1.2	1.8	2.4	V
R _{D(S(ON))}	Static Drain-Source On-Resistance	#REF!		29.4	42.0	mΩ
		V _{GS} =4.5V, I _D =6A		46.2	60.1	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =6A		83		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =18V		0.72	1	V
I _S	Maximum Body-Diode Continuous Current				6	A

DYNAMIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		255	311	pF
C _{oss}	Output Capacitance			45	55	pF
C _{rss}	Reverse Transfer Capacitance			35	41	pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			0.65	Ω

SWITCHING PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =6A		2.55		nC
Q _g 4.5V)	Total Gate Charge			1.275		
Q _{gs}	Gate Source Charge			0.91		
Q _{gd}	Gate Drain Charge			1.3		
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, RL=0.75Ω, R _{GEN} =3Ω		4.25		ns
t _r	Turn-On Rise Time			3.4		
t _{D(off)}	Turn-Off DelayTime			11.9		
t _f	Turn-Off Fall Time			3.825		
t _{rr}	Body Diode Reverse Recovery Time	I _F =-8A, dI/dt=500A/μs		8.5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =18A, dI/dt=500A/μs		2.2		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

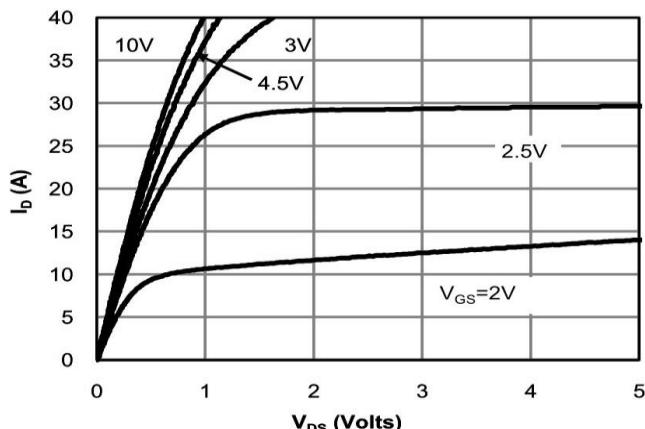


Fig 1: On-Region Characteristics (Note E)

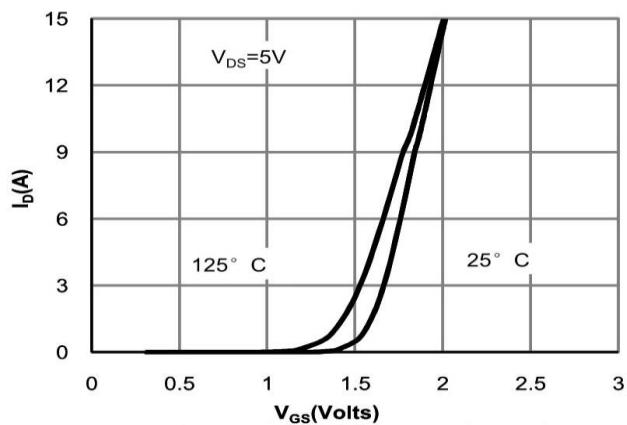


Figure 2: Transfer Characteristics (Note E)

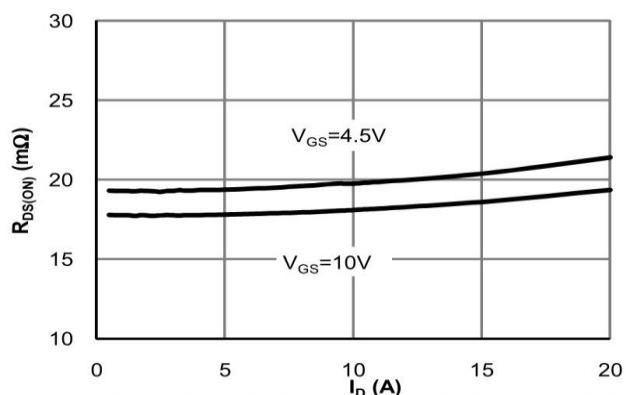


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

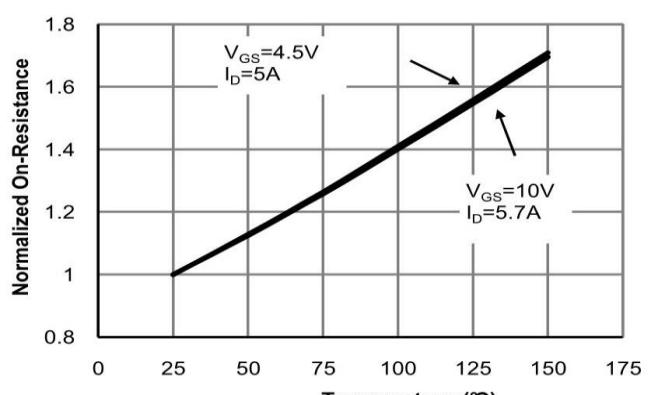


Figure 4: On-Resistance vs. Junction Temperature (Note E)

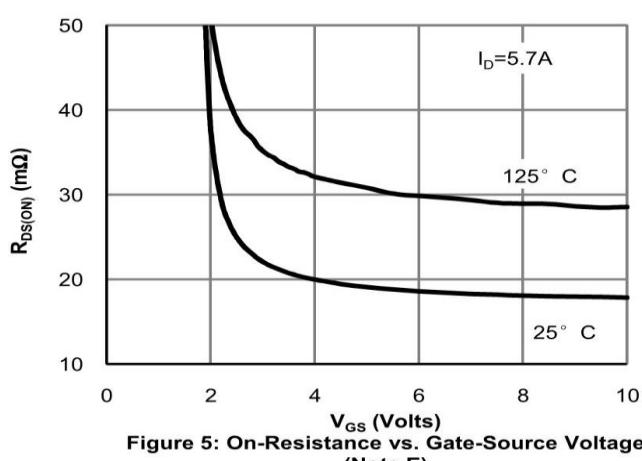


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

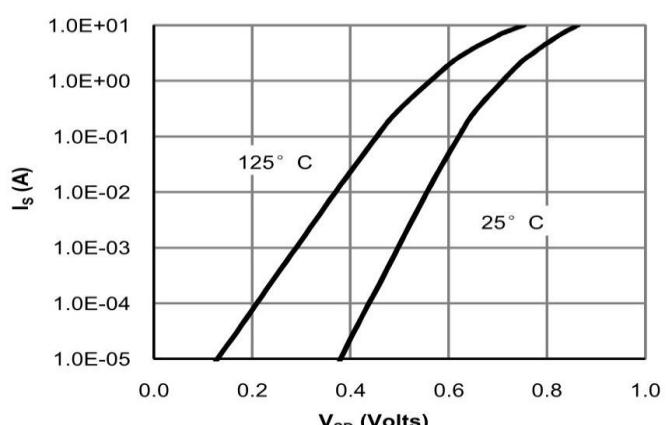


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

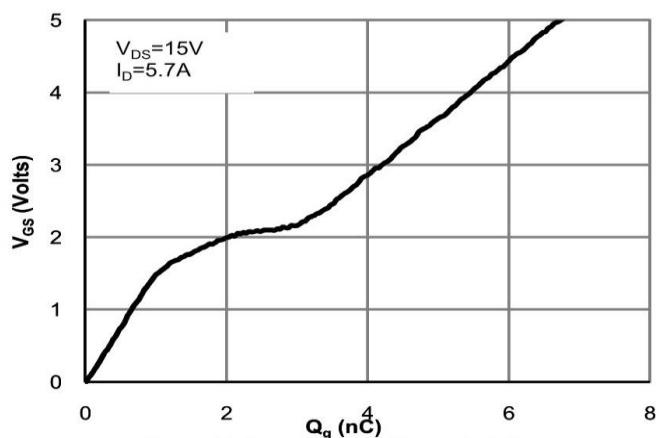


Figure 7: Gate-Charge Characteristics

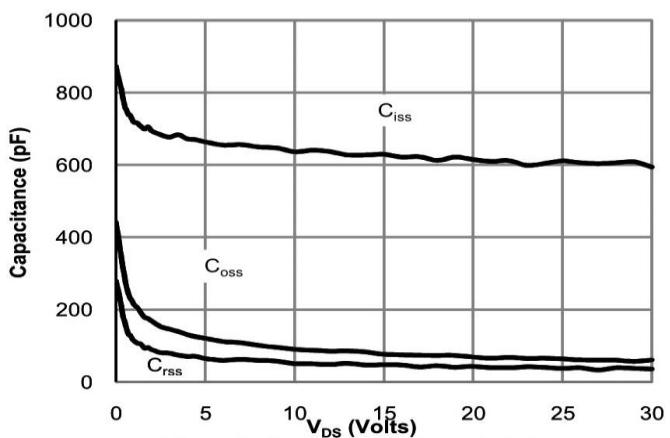


Figure 8: Capacitance Characteristics

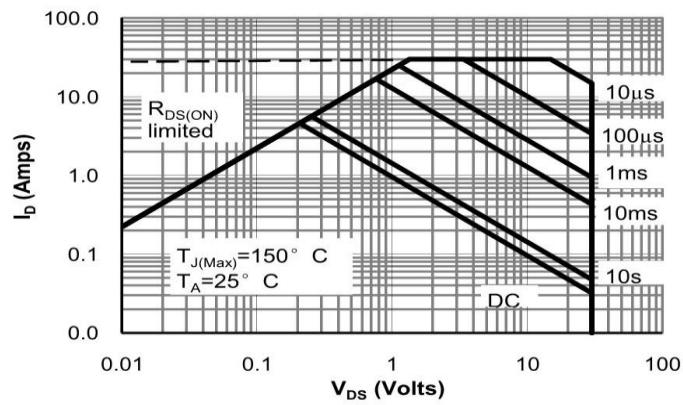


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

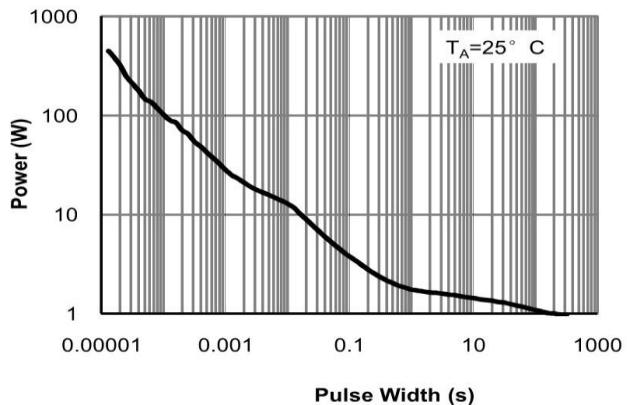


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

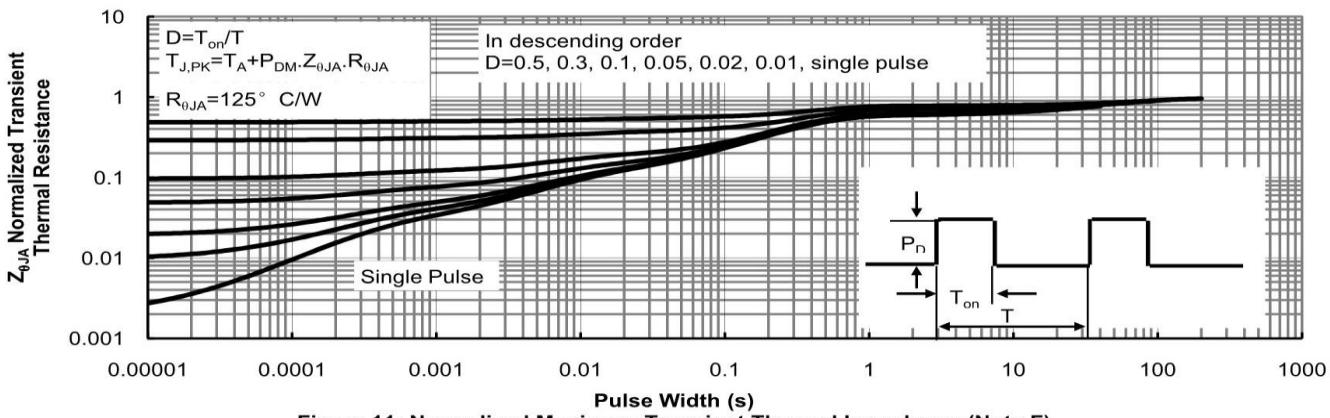


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

STATIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV _{DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	uA
					-5	
I _{GSS}	Gate-Body leakage current	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250μA	-1.2	-1.8	-2.4	V
R _{DSS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, ID=-7A		54.0	54.0	mΩ
		V _{GS} =-4.5V, ID=-7A		59.4	77.2	
g _{FS}	Forward Transconductance	V _{DS} =-5V, ID=-7A		43		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.72	-1	V
I _S	Maximum Body-Diode Continuous Current				-7	A

DYNAMIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz		760	927	pF
C _{oss}	Output Capacitance			140	172	pF
C _{rss}	Reverse Transfer Capacitance			95	113	pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			1.6	Ω

SWITCHING PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Q _g (10V)	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, ID=-7A		6.7		nC
Q _g 4.5V)	Total Gate Charge			3.35		
Q _{gs}	Gate Source Charge			2.24		
Q _{gd}	Gate Drain Charge			3.2		
t _{D(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DS} =-15V, RL=0.75Ω, R _{GEN} =3Ω		7.5		ns
t _r	Turn-On Rise Time			6		
t _{D(off)}	Turn-Off DelayTime			21		
t _f	Turn-Off Fall Time			6.75		
t _{rr}	Body Diode Reverse Recovery Time	I _F =-8A, dI/dt=500A/μs		15		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =18A, dI/dt=500A/μs		9.7		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

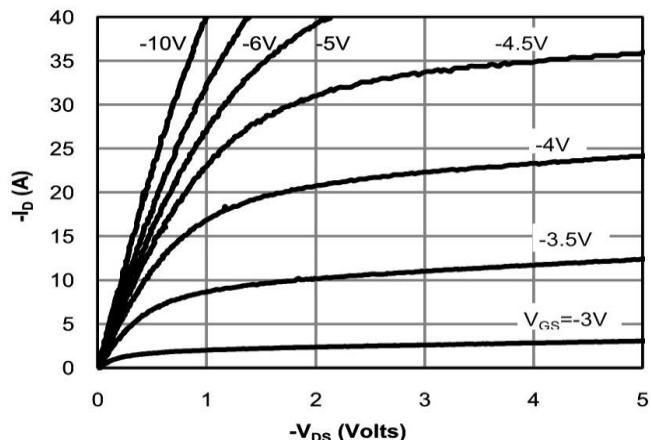


Fig 1: On-Region Characteristics (Note E)

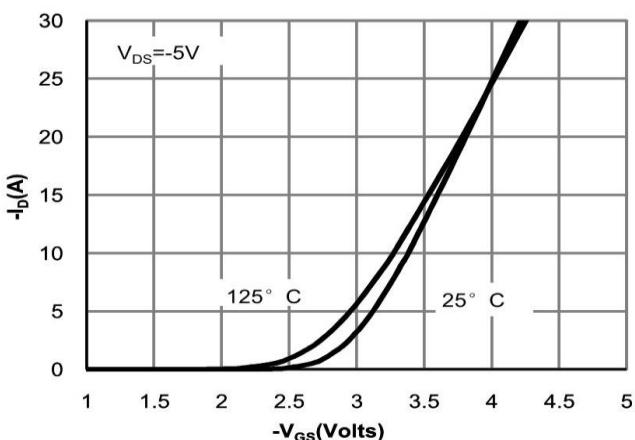


Figure 2: Transfer Characteristics (Note E)

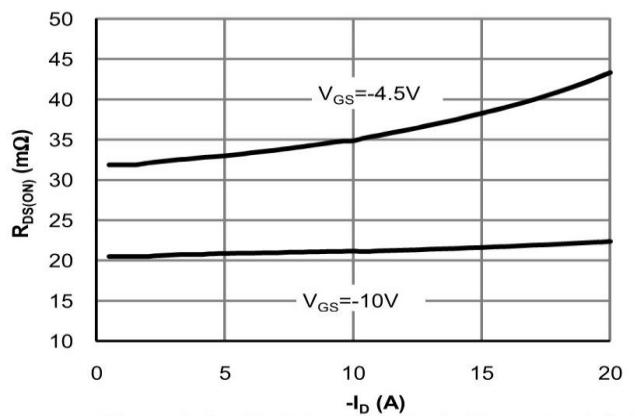


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

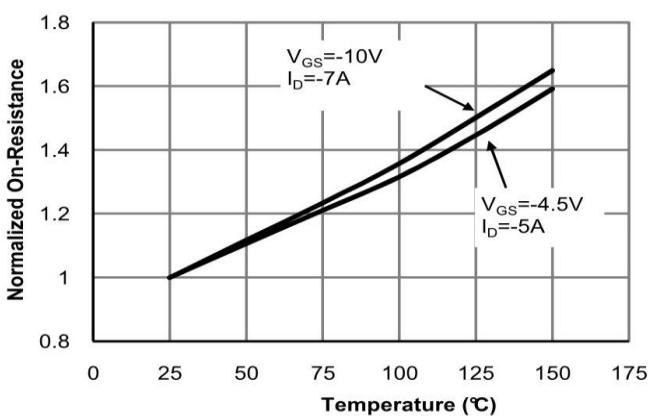


Figure 4: On-Resistance vs. Junction Temperature (Note E)

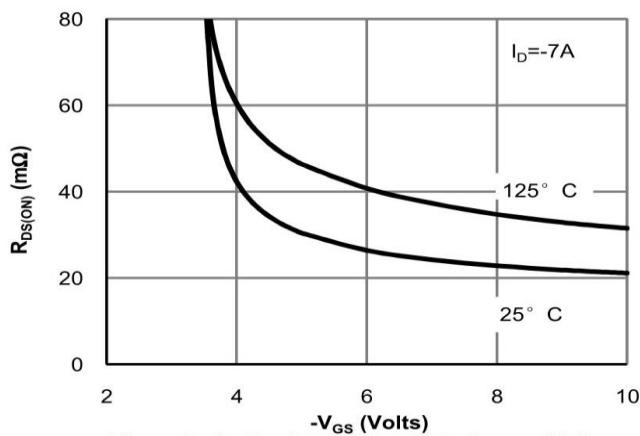


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

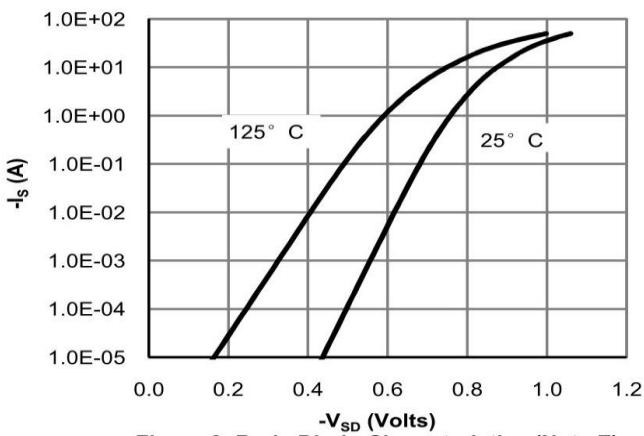


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

